

M5M411860TP-6,-8,-6S,-8S

FAST PAGE MODE 1179648-BIT(65536-WORD BY 18-BIT)DYNAMIC RAM

DESCRIPTION

This is a family of 65536-word by 18-bit dynamic RAMs, fabricated with the high performance CMOS process, and is ideal for large-capacity memory systems where high speed, low power dissipation, and low costs are essential. The use of quadruple-layer polysilicon process combined with silicide technology and a single-transistor dynamic storage stacked capacitor cell provide high circuit density and reduced costs. Multiplexed address inputs permit both a reduction in pins and an increase in system densities.

FEATURES

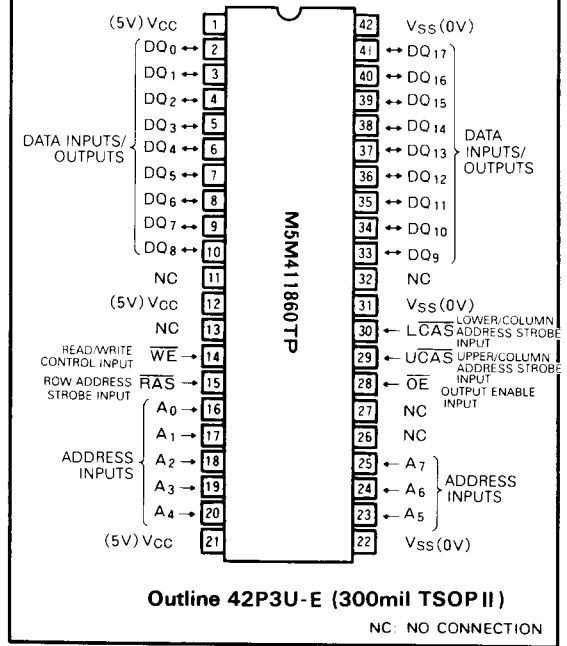
Type name	\overline{RAS} access time (max. ns)	\overline{CAS} access time (max. ns)	Address access time (max. ns)	Cycle time (min. ns)	Power dissipation (max. mW)
M5M411860TP-6,-6S	60	15	30	110	660
M5M411860TP-8,-8S	80	20	40	135	580

- Byte write control can be performed with $1\overline{WE}$ and 2 \overline{CAS} inputs.
- 42 pin 300 mil TSOP (TYPE II)
- Single $5V \pm 10\%$ supply
- Low stand-by power dissipation
2.75mW (max)(CMOS input level)
- Fast-page mode, Read-modify-write, \overline{RAS} -only refresh, \overline{CAS} before \overline{RAS} refresh, Hidden refresh, CBR Self refresh (-6S, -8S) capabilities
- Early write mode and \overline{OE} to control output buffer impedance
- All inputs, outputs TTL compatible and low capacitance
- 256 refresh cycles every 4 ms ($A_0 \sim A_7$)
- 256 refresh cycles every 32ms ($A_0 \sim A_7$)
for Extended Refresh cycle (M5M411860-6S, -8S)

APPLICATION

Storage memory buffer

PIN CONFIGURATION (TOP VIEW)



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FUNCTION

The M5M411860TP provides, in addition to normal read, write, and read-modify-write operations, a number of other functions, e.g., fast-page mode, RAS-only refresh

and delayed-write.

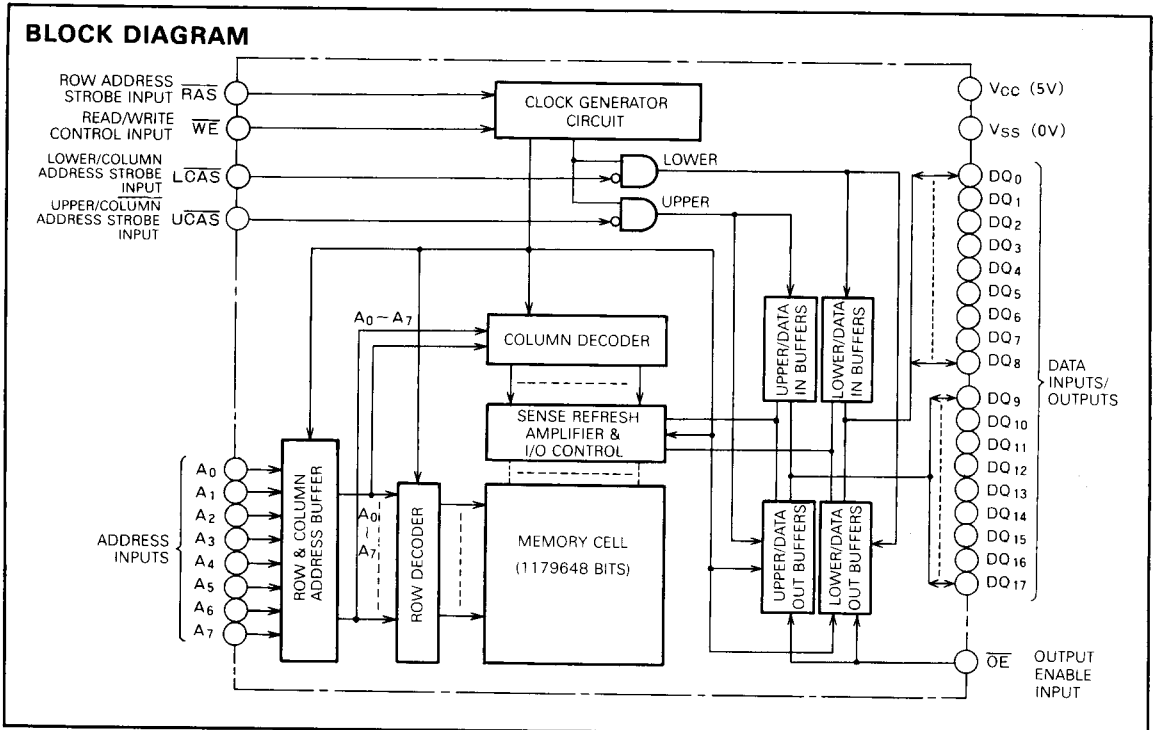
The input conditions for each are shown in Table 1.

Table 1. Input conditions for each mode

Operation	inputs							input/output				Refresh	Remark
	$\overline{\text{RAS}}$	$\overline{\text{LCAS}}$	$\overline{\text{UCAS}}$	$\overline{\text{WE}}$	$\overline{\text{OE}}$	Row address	Column address	Lower		Upper			
								D	Q	D	Q		
Read	ACT	ACT	ACT	NAC	ACT	APD	APD	OPN	VLD	OPN	VLD	YES	Fast-page mode identical
Upper Read	ACT	NAC	ACT	NAC	ACT	APD	APD	DNC	OPN	OPN	VLD	YES	
Lower Read	ACT	ACT	NAC	NAC	ACT	APD	APD	OPN	VLD	DNC	OPN	YES	
Early write	ACT	ACT	ACT	ACT	DNC	APD	APD	VLD	OPN	VLD	OPN	YES	
Upper early	ACT	NAC	ACT	ACT	DNC	APD	APD	DNC	OPN	VLD	OPN	YES	
Lower early	ACT	ACT	NAC	ACT	DNC	APD	APD	VLD	OPN	DNC	OPN	YES	
Delayed write	ACT	ACT	ACT	ACT	ACT	APD	APD	VLD	OPN	VLD	OPN	YES	
Upper delayed	ACT	NAC	ACT	ACT	ACT	APD	APD	DNC	OPN	VLD	OPN	YES	
Lower delayed	ACT	ACT	NAC	ACT	ACT	APD	APD	VLD	OPN	DNC	OPN	YES	
Read-modify-Write	ACT	ACT	ACT	ACT	ACT	APD	APD	VLD	OPN	VLD	OPN	YES	
Upper RMW	ACT	NAC	ACT	ACT	ACT	APD	APD	DNC	OPN	VLD	OPN	YES	
Lower RMW	ACT	ACT	NAC	ACT	ACT	APD	APD	VLD	OPN	DNC	OPN	YES	
<u>RAS</u> only-Refresh	ACT	DNC	DNC	NAC	DNC	APD	DNC	DNC	OPN	DNC	OPN	YES	
Hidden refresh	ACT	ACT	ACT	DNC	ACT	DNC	DNC	OPN	VLD	OPN	VLD	YES	
Upper Hidden-R	ACT	NAC	ACT	DNC	ACT	DNC	DNC	DNC	OPN	OPN	VLD	YES	
Lower Hidden-R	ACT	ACT	NAC	DNC	ACT	DNC	DNC	OPN	VLD	DNC	OPE	YES	
CBR refresh	ACT	ACT	ACT	DNC	DNC	DNC	DNC	DNC	OPN	DNC	OPE	YES	
Upper CBR	ACT	NAC	ACT	DNC	DNC	DNC	DNC	DNC	OPN	DNC	OPN	YES	
Lower CBR	ACT	ACT	NAC	DNC	DNC	DNC	DNC	DNC	OPN	DNC	OPN	YES	
Stand-by	NAC	DNC	DNC	DNC	DNC	DNC	DNC	DNC	OPN	DNC	OPN	NO	

Note: ACT: active, DNC: don't care, VLD: valid, IVD: invalid, APD: applied, OPN: open

BLOCK DIAGRAM



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ABSOLUTE MAXIMUM RATINGS

Symbol	Parameter	Conditions	Ratings	Unit
V _{CC}	Supply voltage	With respect to V _{SS}	-1~7	V
V _I	Input voltage		-1~7	V
V _O	Output voltage		-1~7	V
I _O	Output current		50	mA
P _d	Power dissipation	T _a = 25°C	1000	mW
T _{opr}	Operating temperature		0~70	°C
T _{stg}	Storage temperature		-65~150	°C

RECOMMENDED OPERATING CONDITIONS (T_a = 0~70°C unless otherwise noted) (Note 1)

Symbol	Parameter	Limits			Unit
		Min	Nom	Max	
V _{CC}	Supply voltage	4.5	5	5.5	V
V _{SS}	Supply voltage	0	0	0	V
V _{IH}	High-level input voltage, all inputs	2.4		6.5	V
V _{IL}	Low-level input voltage, all inputs	-1.0		0.8	V

Note 1: All voltage values are with respect to V_{SS}

ELECTRICAL CHARACTERISTICS (T_a = 0~70°C, V_{CC} = 5V ± 10%, V_{SS} = 0V, unless otherwise noted) (Note 2)

Symbol	Parameter	Test conditions	Limits			Unit
			Min	Typ	Max	
V _{OH}	High level output voltage	I _{OH} = -2.5mA	2.4		V _{CC}	V
V _{OL}	Low-level output voltage	I _{OL} = 2.1mA	0		0.4	V
I _{OZ}	Off-state output current	Q floating 0V ≤ V _{OUT} ≤ 5.5V	-10		10	μA
I _I	Input current	0 ≤ V _{IN} ≤ 6.5V, Other input pins = 0V	-10		10	μA
I _{CC1(AV)}	Average supply current from V _{CC} operating (Note 3, 4)	M5M411860-6, -6S			120	mA
		M5M411860-8, -8S			105	
I _{CC2}	Supply current from V _{CC} Stand-by	M5M411860-6, -8	RAS = CAS cycling		2	mA
		M5M411860-6S, -8S	RAS = CAS = V _{IH} , output open		2	
		M5M411860-6, -8	RAS = CAS = WE = OE ≥ V _{CC} - 0.5		0.5	
		M5M411860-6S, -8S	output open		0.1	
I _{CC3(AV)}	Average supply current from V _{CC} refreshing (Note 3)	M5M411860-6, -6S	RAS cycling, CAS = V _{IH} , t _{RC} = min		120	mA
		M5M411860-8, -8S	output open		105	
I _{CC4(AV)}	Average supply current from V _{CC} Fast-Page-Mode (Note 3, 4)	M5M411860-6, -6S	RAS = V _{IL} , CAS = cycling, t _{PC} = min		95	mA
		M5M411860-8, -8S	output open		80	
I _{CC6(AV)}	Average supply current from V _{CC} CAS before RAS refresh mode (Note 3)	M5M411860-6, -6S	CAS before RAS refresh cycling		80	mA
		M5M411860-8, -8S	t _{RC} = min, output open		65	

ELECTRICAL CHARACTERISTICS (continued)

Self-Refresh M5M411860-6S, -8S (T_a = 0~70°C, V_{CC} = 5V ± 10%, V_{SS} = 0V, unless otherwise noted) (Note 2)

Symbol	Parameter	Test conditions	Limits			Unit
			Min	Typ	Max	
I _{CC8}	Average supply current from V _{CC} Battery Back-up (Extended Refreshing)	CAS = 0.2V or CAS before RAS cycling, WE, A ₀₋₇ , Din = V _{CC} - 0.2V or 0.2V, Q = OPEN, t _{RC} = 125μs, t _{RAS} = t _{RAS(min)} - 1μs.			200	μA
I _{CC9}	Average supply current from V _{CC} , Self-Refresh cycle	RAS = CAS = 0.2V			100	μA

Note 2: Current flowing into an IC is positive, out is negative.

3: I_{CC1}, I_{CC3}, I_{CC4}, I_{CC6} are dependent on cycle rate. Maximum current is measured at the fastest cycle rate.

4: I_{CC1} and I_{CC4} are dependent on output loading. Specified values are obtained with the output open.

CAPACITANCE (T_a = 0~70°C, V_{CC} = 5V ± 10%, V_{SS} = 0V unless otherwise noted)

Symbol	Parameter	Test conditions	Limits			Unit
			Min	Typ	Max	
C _{I(A)}	Input capacitance, address inputs	V _I = V _{SS} , f = 1MHz, V _I = 25mVrms			5	pF
C _{I(CLK)}	Input capacitance, clock inputs				7	pF
C _{I/O}	Input/output capacitance, data ports				7	pF

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SWITCHING CHARACTERISTICS (Ta=0~70°C, VCC=5V±10%, VSS=0V, unless otherwise noted. See notes 5, 12, 13)

Symbol	Parameter	Limits				Unit
		M5M411860-6, -6S		M5M411860-8, -8S		
		Min	Max	Min	Max	
t _{OAC}	Access time from $\overline{\text{CAS}}$ (Note 6, 7)		15		20	ns
t _{RAC}	Access time from $\overline{\text{RAS}}$ (Note 6, 8)		60		80	ns
t _{AA}	Column address access time (Note 6, 9)		30		40	ns
t _{CPA}	Access time from $\overline{\text{CAS}}$ precharge (Note 6, 10)		35		45	ns
t _{OEA}	Access time from $\overline{\text{OE}}$ (Note 6)		15		20	ns
t _{CLZ}	Output low impedance time from $\overline{\text{CAS}}$ low (Note 6)	5		5		ns
t _{OFF}	Output disable time after $\overline{\text{CAS}}$ high (Note 11)	0	15	0	20	ns
t _{OEZ}	Output disable time after $\overline{\text{OE}}$ high (Note 11)	0	10	0	10	ns

Note 5: An initial pause of 500 μ s is required after power-up followed by a minimum of eight initialization cycles (any combination of cycles containing a $\overline{\text{RAS}}$ clock such as $\overline{\text{RAS}}$ -Only refresh).

Note the $\overline{\text{RAS}}$ may be cycled during the initial pause. And any 8 $\overline{\text{RAS}}$ or $\overline{\text{RAS}}/\overline{\text{CAS}}$ cycles are required after prolonged periods (greater than 4ms) of $\overline{\text{RAS}}$ inactivity before proper device operation is achieved.

6: Measured with a load circuit equivalent to 1TTL load and 30pF.

7: Assumes that $t_{\text{RCD}} \geq t_{\text{RCD(max)}}$ and $t_{\text{ASC}} \geq t_{\text{ASC(max)}}$.

8: Assumes that $t_{\text{RCD}} \leq t_{\text{RCD(max)}}$ and $t_{\text{RAD}} \leq t_{\text{RAD(max)}}$. If t_{RCD} or t_{RAD} is greater than the maximum recommended value shown in this table, t_{RAC} will increase by amount that t_{RCD} or t_{RAD} exceed the value shown.

9: Assumes that $t_{\text{RAD}} \geq t_{\text{RAD(max)}}$ and $t_{\text{ASC}} \leq t_{\text{ASC(max)}}$. If t_{ASC} is greater than the maximum recommended value shown in this table, t_{AA} will increase by amount that t_{ASC} exceeds the value shown.

10: Assumes that $t_{\text{ASC}} \geq t_{\text{ASC(max)}}$ and $t_{\text{CP}} \leq t_{\text{CP(max)}}$. If $t_{\text{ASC}} \geq t_{\text{ASC(max)}}$ and $t_{\text{CP}} \geq t_{\text{CP(max)}}$, access time (t_{CPA}) is controlled by t_{CAC} . If $t_{\text{ASC}} \leq t_{\text{ASC(max)}}$ and $t_{\text{CP}} \geq t_{\text{CP(max)}}$ or $t_{\text{ASC}} \leq t_{\text{ASC(max)}}$ and $t_{\text{CP}} \leq t_{\text{CP(max)}}$, access time (t_{CPA}) is controlled by t_{AA} .

11: $t_{\text{OFF(max)}}$ and $t_{\text{OEZ(max)}}$ defines the time at which the output achieves the high impedance state ($|I_{\text{OUT}}| \leq 10\mu\text{A}$) and is not reference to $V_{\text{OH(min)}}$ or $V_{\text{OL(max)}}$.

TIMING REQUIREMENTS (For Read, Write, Read-Modify-Write, Refresh, and Fast page Cycles)

(Ta=0~70°C, VCC=5V±10%, VSS=0V, unless otherwise noted. See notes 11, 12)

Symbol	Parameter	Limits				Unit
		M5M411860-6, -6S		M5M411860-8, -8S		
		Min	Max	Min	Max	
t _{REF}	Refresh cycle time		4(32)*		4(32)*	ms
t _{RP}	$\overline{\text{RAS}}$ high pulse width	40		45		ns
t _{RCD}	Delay time, $\overline{\text{RAS}}$ low to $\overline{\text{CAS}}$ low	20	45	20	60	ns
t _{CRP}	Delay time, $\overline{\text{CAS}}$ high to $\overline{\text{RAS}}$ low (Note 14)	5		5		ns
t _{RPC}	Delay time, $\overline{\text{RAS}}$ high to $\overline{\text{CAS}}$ low	0		0		ns
t _{CPN}	$\overline{\text{CAS}}$ high pulse width	10		10		ns
t _{RAD}	Column address delay time from $\overline{\text{RAS}}$ low (Note 15)	15	30	15	40	ns
t _{ASR}	Row address setup time before $\overline{\text{RAS}}$ low	0		0		ns
t _{ASC}	Column address setup time before $\overline{\text{CAS}}$ low (Note 16)	0	10	0	15	ns
t _{RAH}	Row address hold time after $\overline{\text{RAS}}$ low	10		10		ns
t _{CAH}	Column address hold time after $\overline{\text{CAS}}$ low	15		15		ns
t _{DZC}	Delay time, data to $\overline{\text{CAS}}$ low (Note 17)	0		0		ns
t _{DZO}	Delay time, data to $\overline{\text{OE}}$ low (Note 17)	0		0		ns
t _{CDD}	Delay time, $\overline{\text{CAS}}$ high to data (Note 18)	15		20		ns
t _{ODD}	Delay time, $\overline{\text{OE}}$ high to data (Note 18)	10		10		ns
t _T	Transition time (Note 19)	1	50	1	50	ns

*: t_{REF} (32ms) is for Extended Refresh cycle (M5M411860-6S, -8S)

Note 12: The timing requirements are assumed t_T=5ns.

13: V_{IH(min)} and V_{IL(max)} are reference levels for measuring timing of input signals.

14: t_{RCD(max)} is specified as a reference point only.

If t_{RCD} is greater than t_{RCD(max)}, access time is controlled by t_{CAC} or t_{AA}.

15: t_{RAD(max)} is specified as a reference point only. If t_{RAD} ≥ t_{RAD(max)} and t_{ASC} ≤ t_{ASC(max)}, access time is controlled by t_{AA}.

16: t_{ASC(max)} is specified as a reference point only. If t_{RCD} ≥ t_{RCD(max)} and t_{ASC} ≥ t_{ASC(max)}, t_{AA} is controlled by t_{CAC}.

17: Either t_{DZC} or t_{DZO} must be satisfied.

18: Either t_{CDD} or t_{ODD} must be satisfied.

19: t_T is measured between V_{IH(min)} and V_{IL(max)}.

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Read and Refresh Cycles

Symbol	Parameter	Limits				Unit
		M5M411860-6, -6S		M5M411860-8, -8S		
		Min	Max	Min	Max	
t _{RC}	Read cycle time	110		135		ns
t _{RAS}	RAS low pulse width	60	10000	80	10000	ns
t _{CAS}	CAS low pulse width	15	10000	20	10000	ns
t _{CSH}	CAS hold time after RAS low	60		80		ns
t _{RSH}	RAS hold time after CAS low	15		20		ns
t _{RCS}	Read Setup time before CAS low	0		0		ns
t _{RCH}	Read hold time after CAS high (Note 20)	0		0		ns
t _{RRH}	Read hold time after RAS high (Note 20)	0		0		ns
t _{RAL}	Column address to RAS hold time	30		40		ns
t _{OCH}	CAS hold time after OE low	15		20		ns
t _{ORH}	RAS hold time after OE low	10		10		ns

Note 20: Either t_{RCH} or t_{RRH} must be satisfied for a read cycle.

Write Cycle (Early Write and Delayed Write)

Symbol	Parameter	Limits				Unit
		M5M411860-6, -6S		M5M411860-8, -8S		
		Min	Max	Min	Max	
t _{WC}	Write cycle time	110		135		ns
t _{RAS}	RAS low pulse width	60	10000	80	10000	ns
t _{CAS}	CAS low pulse width	15	10000	20	10000	ns
t _{CSH}	CAS hold time after RAS low	60		80		ns
t _{RSH}	RAS hold time after CAS low	15		20		ns
t _{WCS}	Write setup time before CAS low (Note 22)	0		0		ns
t _{WCH}	Write hold time after CAS low	10		15		ns
t _{CWL}	CAS hold time after W low	15		20		ns
t _{RWL}	RAS hold time after W low	15		20		ns
t _{WP}	Write pulse width	10		15		ns
t _{DS}	Date setup time before CAS low or W low	0		0		ns
t _{DH}	Date hold time after CAS low or W low	10		15		ns
t _{OEH}	OE hold time after W low	10		10		ns

Read-Write and Read-Modify-Write Cycles

Symbol	Parameter	Limits				Unit
		M5M411860-6, -6S		M5M411860-8, -8S		
		Min	Max	Min	Max	
t _{RWC}	Read write/read modify write cycle time (Note 21)	145		175		ns
t _{RAS}	RAS low pulse width	100	10000	120	10000	ns
t _{CAS}	CAS low pulse width	50	10000	60	10000	ns
t _{CSH}	CAS hold time after RAS low	95		120		ns
t _{RSH}	RAS hold time after CAS low	50		60		ns
t _{RCS}	Read setup time before CAS low	0		0		ns
t _{CWD}	Delay time, CAS low to W low (Note 22)	30		35		ns
t _{RWD}	Delay time, RAS low to W low (Note 22)	75		95		ns
t _{AWD}	Delay time, address to W low (Note 22)	45		55		ns
t _{CWL}	CAS hold time after W low	15		20		ns
t _{RWL}	RAS hold time after W low	15		20		ns
t _{WP}	Write pulse width	10		15		ns
t _{DS}	Date setup time before W low	0		0		ns
t _{DH}	Date hold time after W low	10		15		ns
t _{OEH}	OE hold time after W low	10		10		ns

Note 21: t_{RWC} is specified as t_{RWC(min)} = t_{RAC(max)} + t_{ODD(min)} + t_{RWL(min)} + t_{RP(min)} + 4t_r

22: t_{WCS}, t_{CWD}, t_{RWD}, t_{AWD} and t_{CPWD} are specified as reference points only. If t_{WCS} ≥ t_{WCS(min)} the cycle is an early write cycle and the DQ pins will remain high impedance throughout the entire cycle. If t_{CWD} ≥ t_{CWD(min)}, t_{RWD} ≥ t_{RWD(min)}, t_{AWD} ≥ t_{AWD(min)} and t_{CPWD} ≥ t_{CPWD(min)} (for fast page mode cycle only), the cycle is a read-modify-write cycle and the DQ will contain the data read from the selected address. If neither of the above condition is satisfied (delayed write), the condition of DQ (at access time and until CAS or OE goes back to V_{ih}) is indeterminate.

M5M411860TP-6,-8,-6S,-8S**FAST PAGE MODE 1179648-BIT(65536-WORD BY 18-BIT)DYNAMIC RAM****Fast-Page Mode Cycle (Read, Early Write, Read-Write, Read-Modify-Write Cycle) (Note 23)**

Symbol	Parameter	Limits				Unit
		M5M411860-6, -6S		M5M411860-8, -8S		
		Min	Max	Min	Max	
t_{PC}	Fast page mode read/write cycle time	40		50		ns
t_{PRWC}	Fast page mode read write/read modify write cycle time	75		100		ns
t_{RAS}	\overline{RAS} low pulse width for read write cycle	100	100000	130	100000	ns
t_{CP}	\overline{CAS} high pulse width (Note 25)	10	15	10	20	ns
t_{CPRH}	\overline{RAS} hold time after \overline{CAS} precharge	35		45		ns
t_{CPWD}	Delay time, \overline{CAS} precharge to \overline{W} low	50		60		ns

Note 23; All previously specified timing requirements and switching characteristics are applicable to their respective fast page mode cycle.

24; $t_{RAS(min)}$ is specified as two cycles of \overline{CAS} input are performed. $t_{RAS(min)} = t_{CSH(min)} \pm t_{PC(min)}$

25; $t_{CP(max)}$ is specified as a reference point only.

 \overline{CAS} before \overline{RAS} Refresh Cycle (Note 26)

Symbol	Parameter	Limits				Unit
		M5M411860-6, -6S		M5M411860-8, -8S		
		Min	Max	Min	Max	
t_{CSR}	\overline{CAS} setup time before \overline{RAS} low	5		5		ns
t_{CHR}	\overline{CAS} hold time after \overline{RAS} low	10		10		ns

Note 26; Eight or more \overline{CAS} before \overline{RAS} cycles instead of eight \overline{RAS} cycles are necessary for proper operation of \overline{CAS} before \overline{RAS} refresh mode.

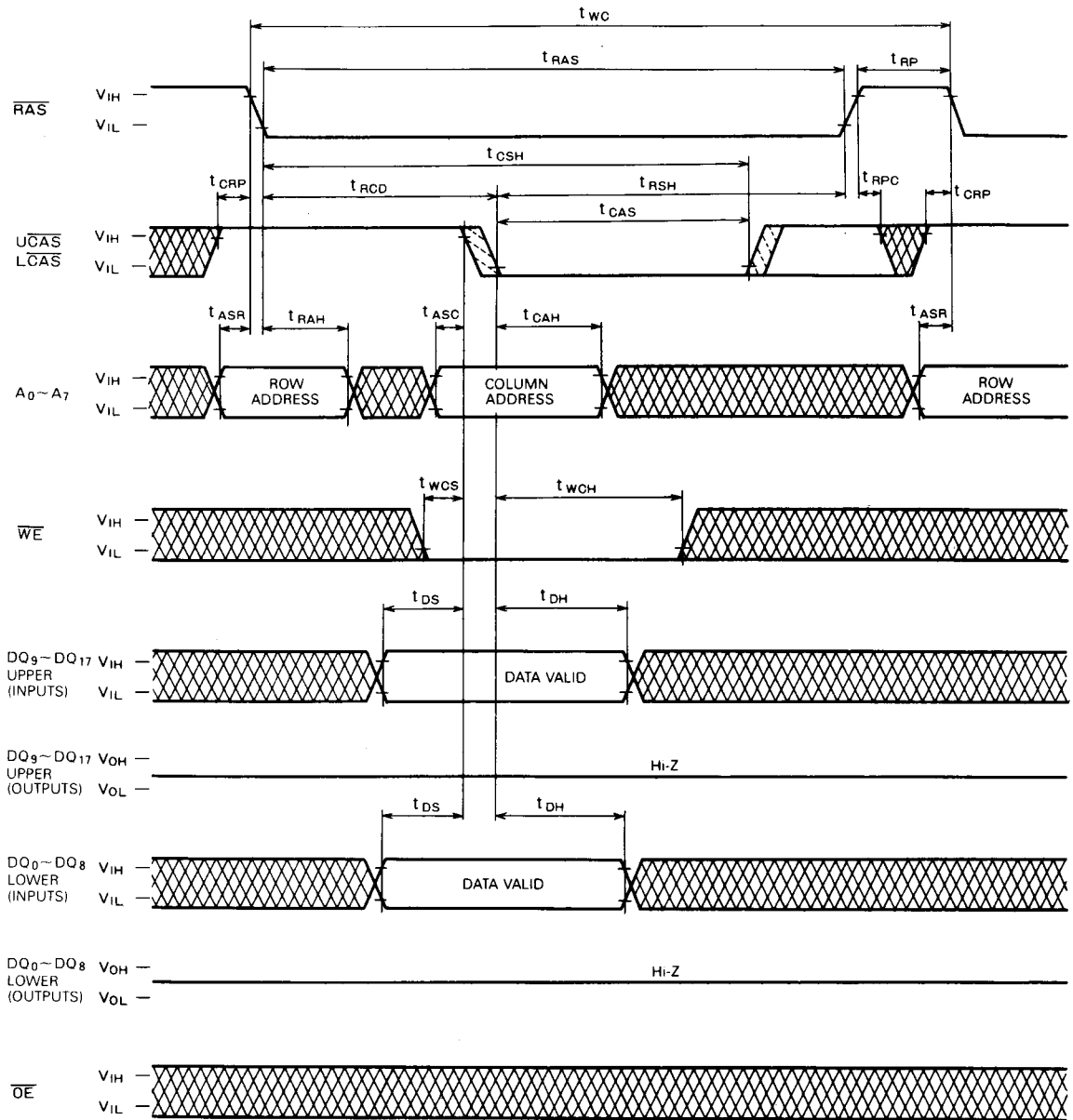
 \overline{CAS} before \overline{RAS} Self Refresh Cycle (M5M411860-6S, -8S)

Symbol	Parameter	Limits				Unit
		M5M411860-6S		M5M411860-8S		
		Min	Max	Min	Max	
t_{RASS}	\overline{RAS} low pulse time	100		100		μ s
t_{RPS}	\overline{RAS} high precharge time	110		135		ns
t_{CHS}	\overline{CAS} hold time	-50		-50		ns

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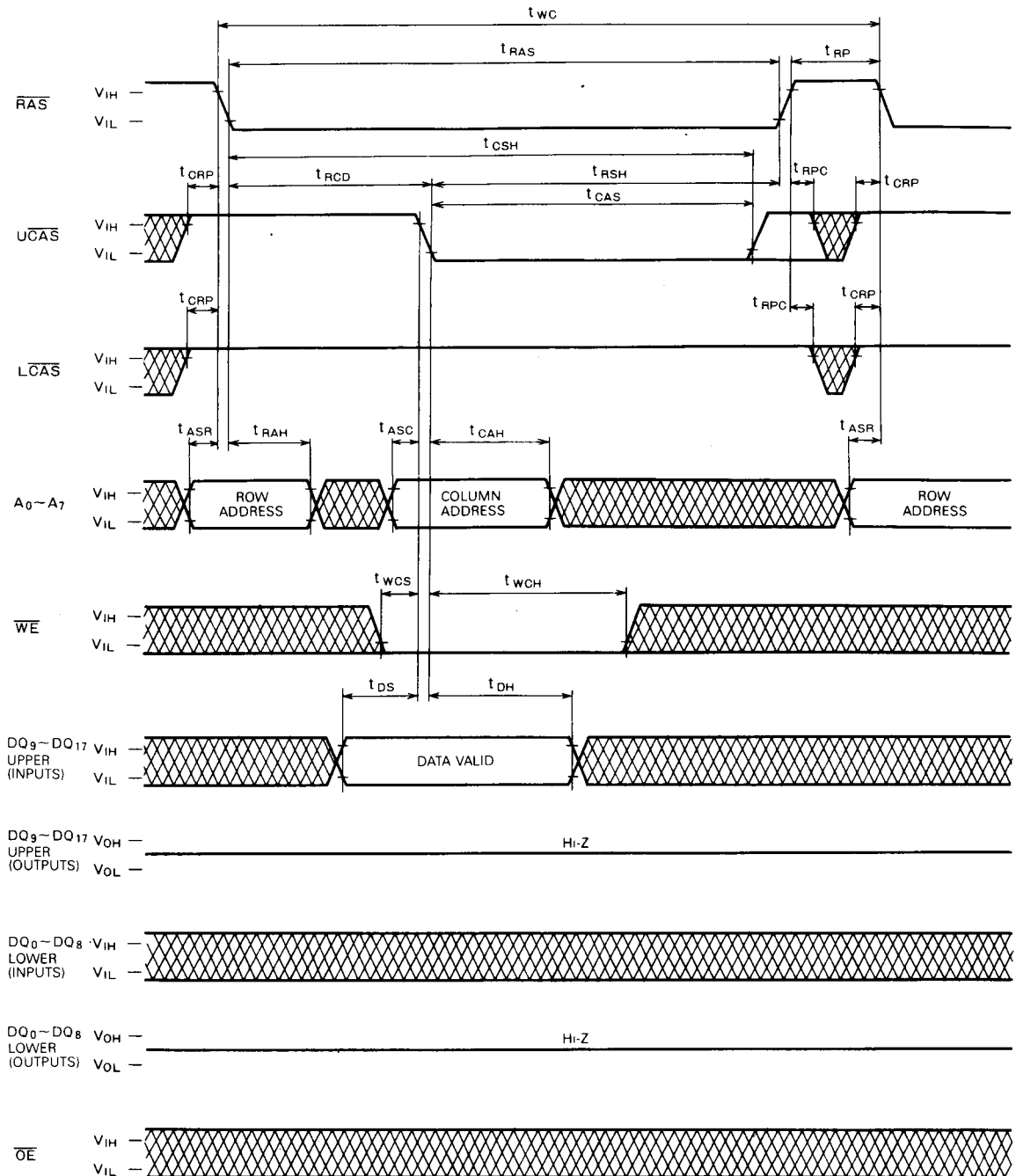
Early Write Cycle



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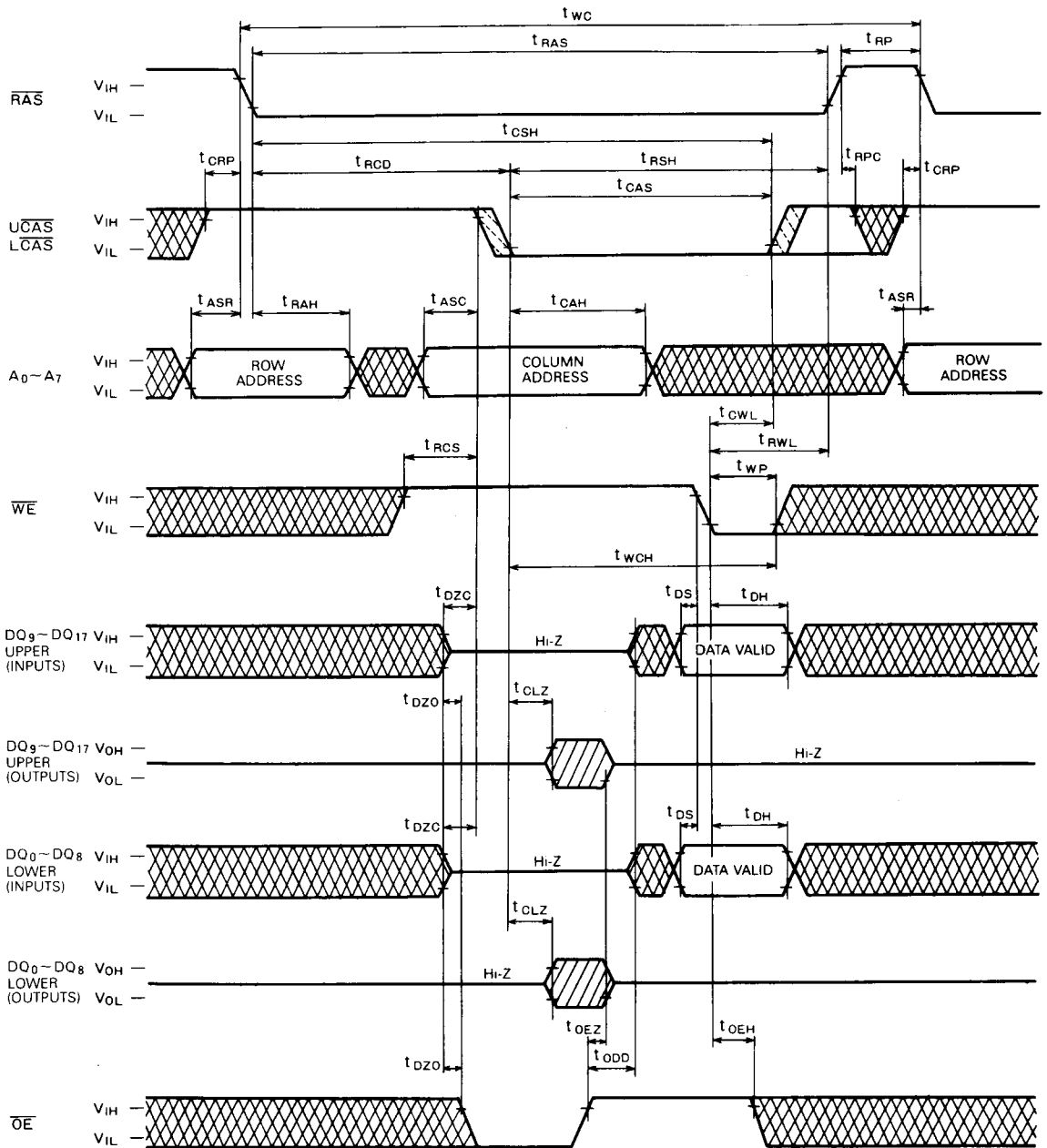
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Early Write Upper (Lower) Byte Write Cycle



FAST PAGE MODE 1179648-BIT(65536-WORD BY 18-BIT)DYNAMIC RAM

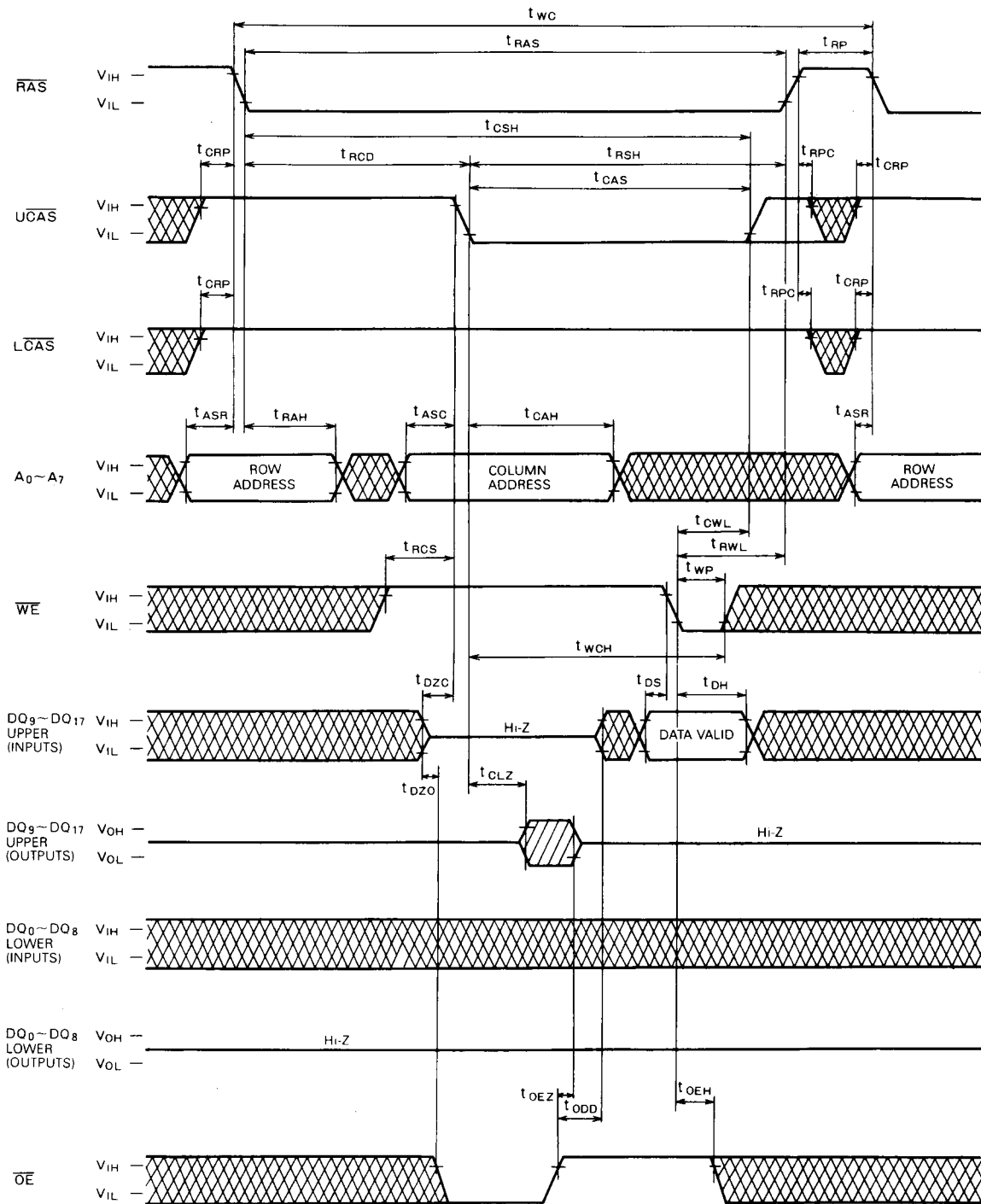
Delayed Write Cycle



M5M411860TP-6,-8,-6S,-8S

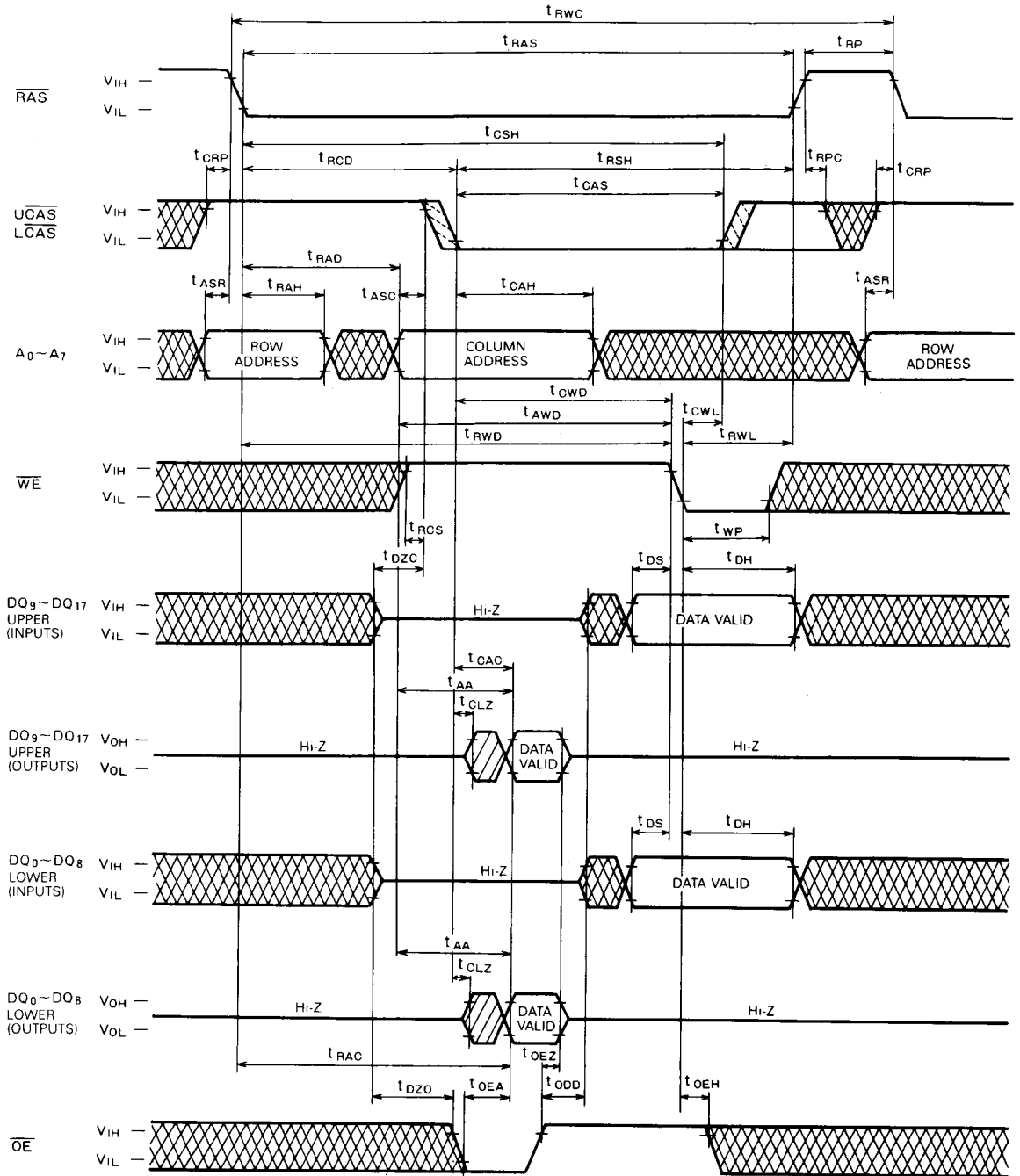
FAST PAGE MODE 1179648-BIT(65536-WORD BY 18-BIT)DYNAMIC RAM

Delayed Write Upper (Lower) Byte Cycle



FAST PAGE MODE 1179648-BIT(65536-WORD BY 18-BIT)DYNAMIC RAM

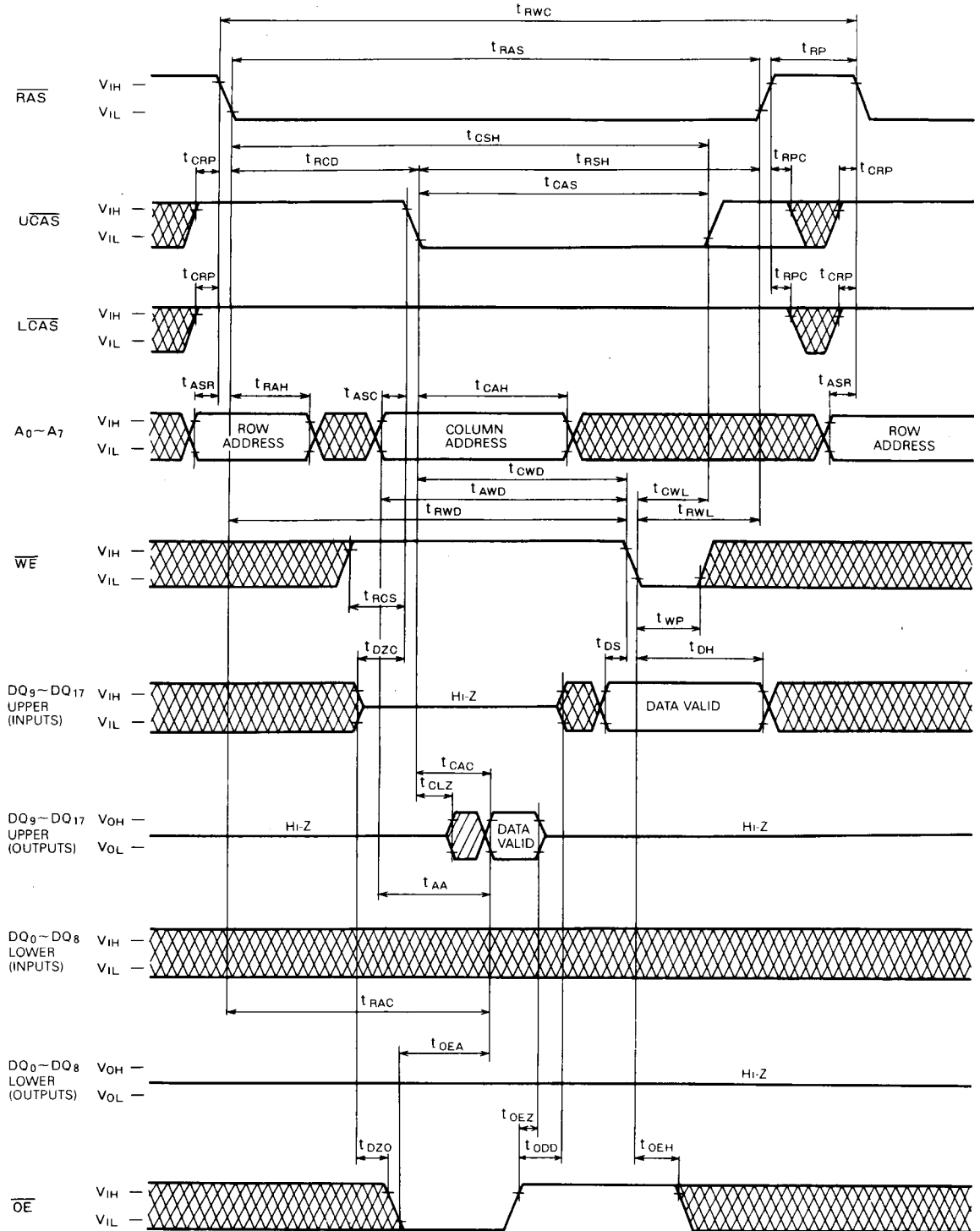
Read-Modify-Write Cycle



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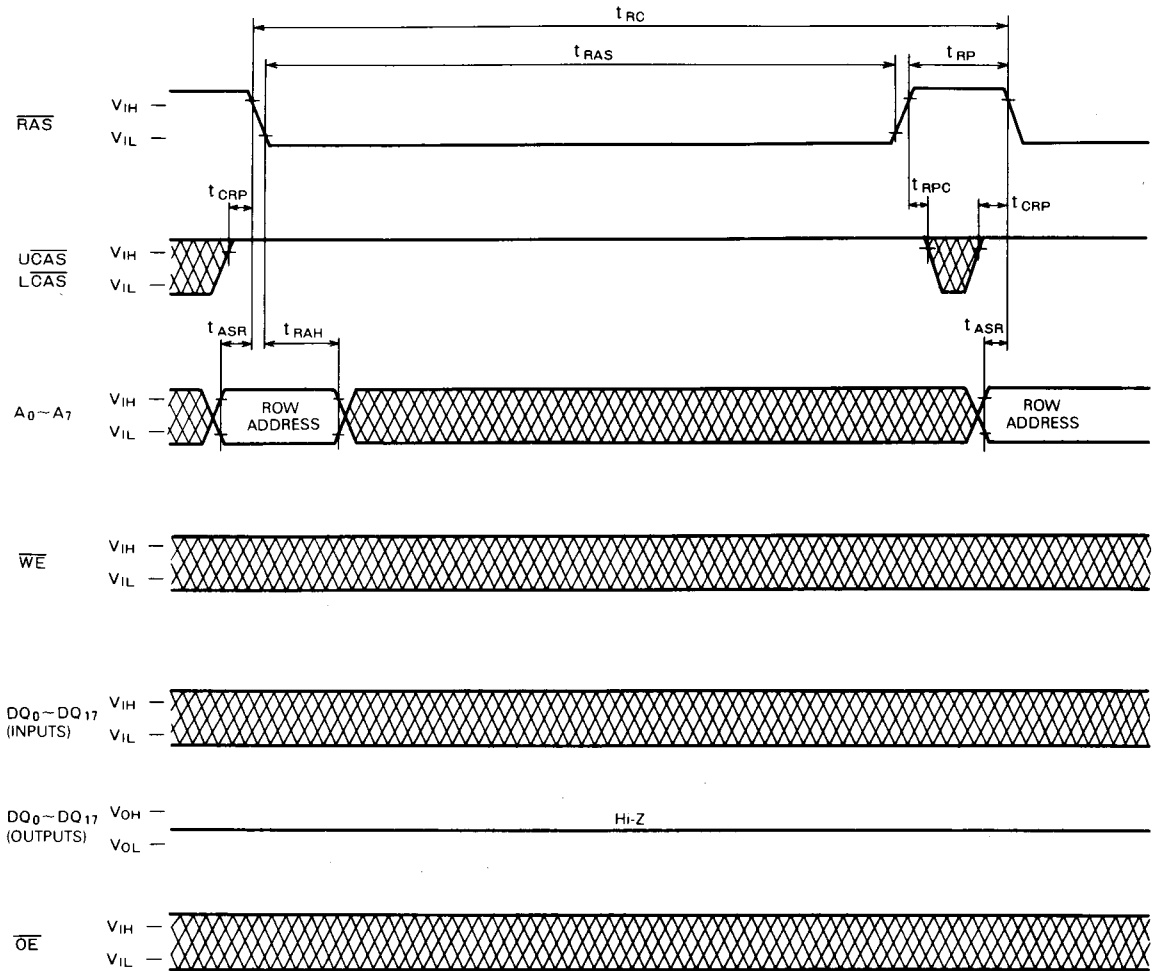
Read Modify Upper (Lower) Byte Cycle



M5M411860TP-6,-8,-6S,-8S

FAST PAGE MODE 1179648-BIT(65536-WORD BY 18-BIT)DYNAMIC RAM

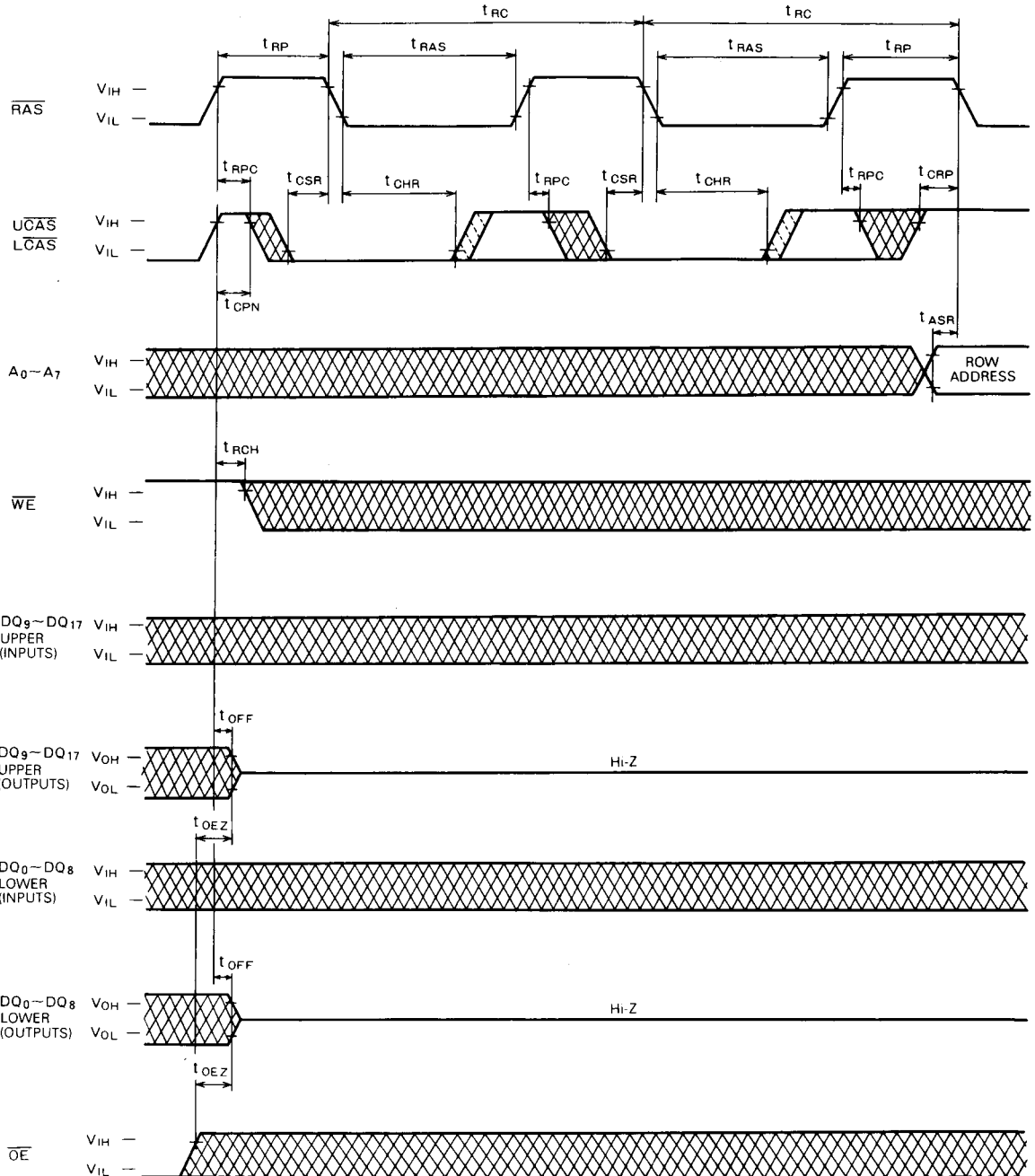
RAS-only Refresh



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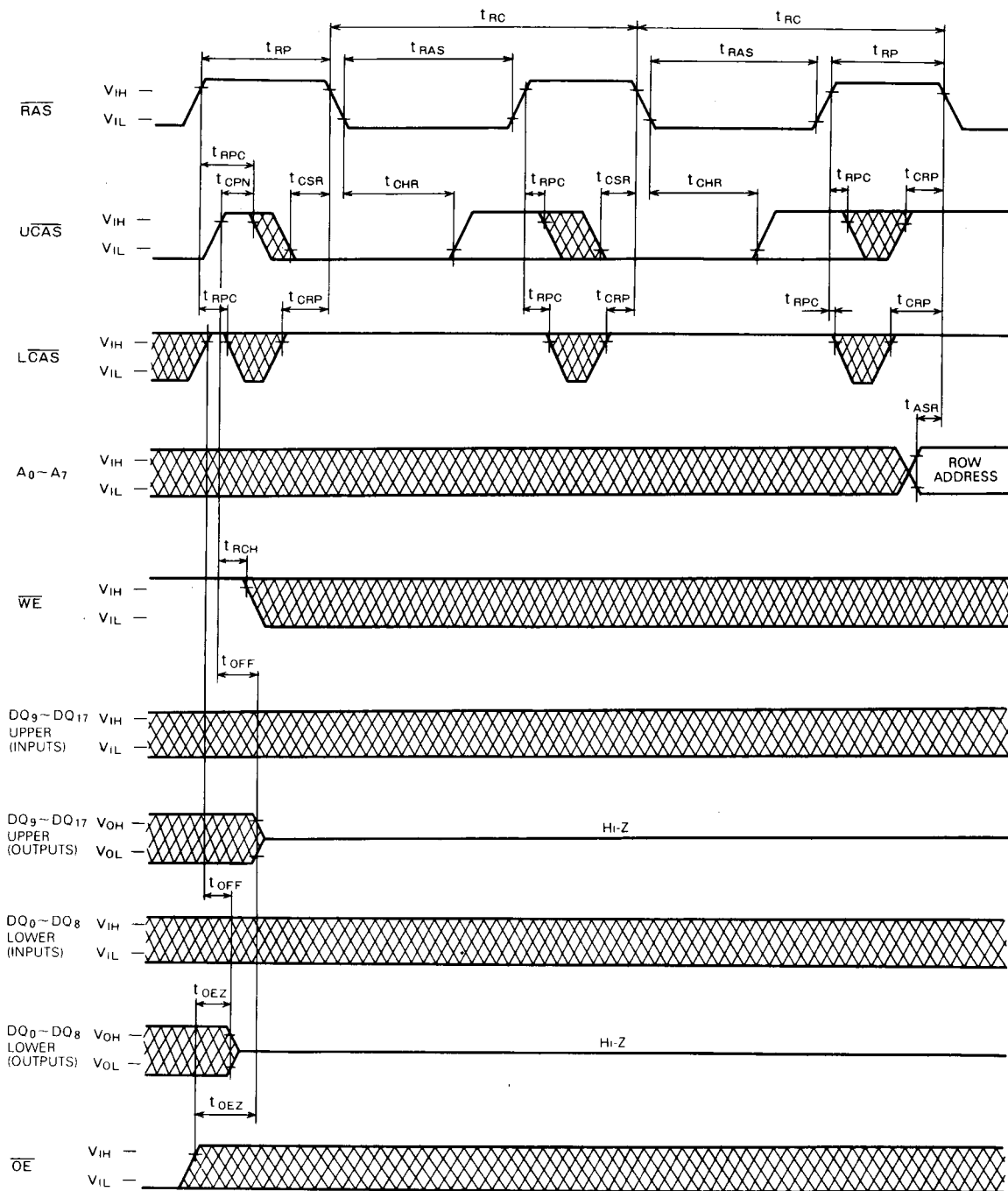
FAST PAGE MODE 1179648-BIT(65536-WORD BY 18-BIT)DYNAMIC RAM

$\overline{\text{CAS}}$ before $\overline{\text{RAS}}$ Refresh Cycle



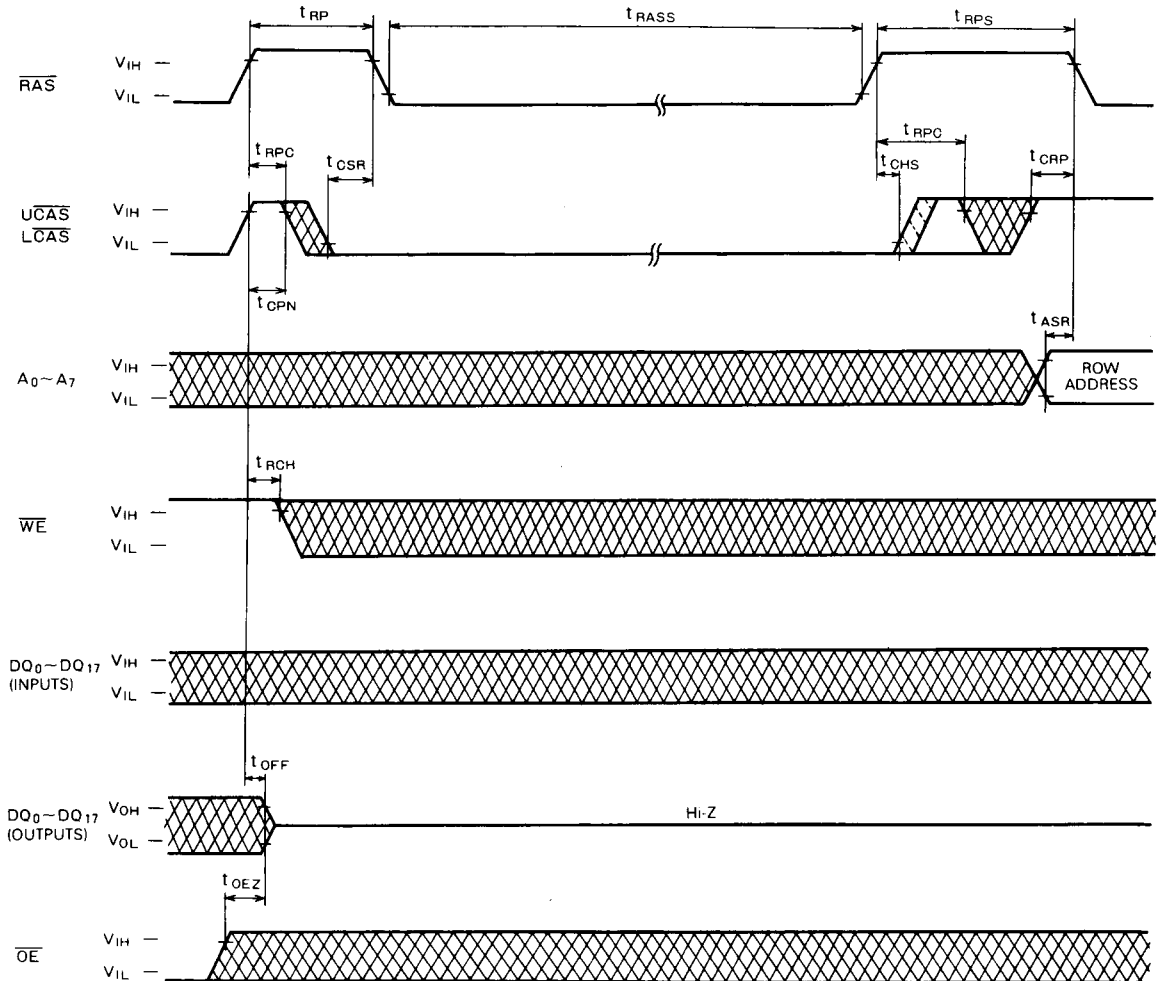
FAST PAGE MODE 1179648-BIT(65536-WORD BY 18-BIT)DYNAMIC RAM

Upper (Lower) CAS before RAS Refresh Cycle

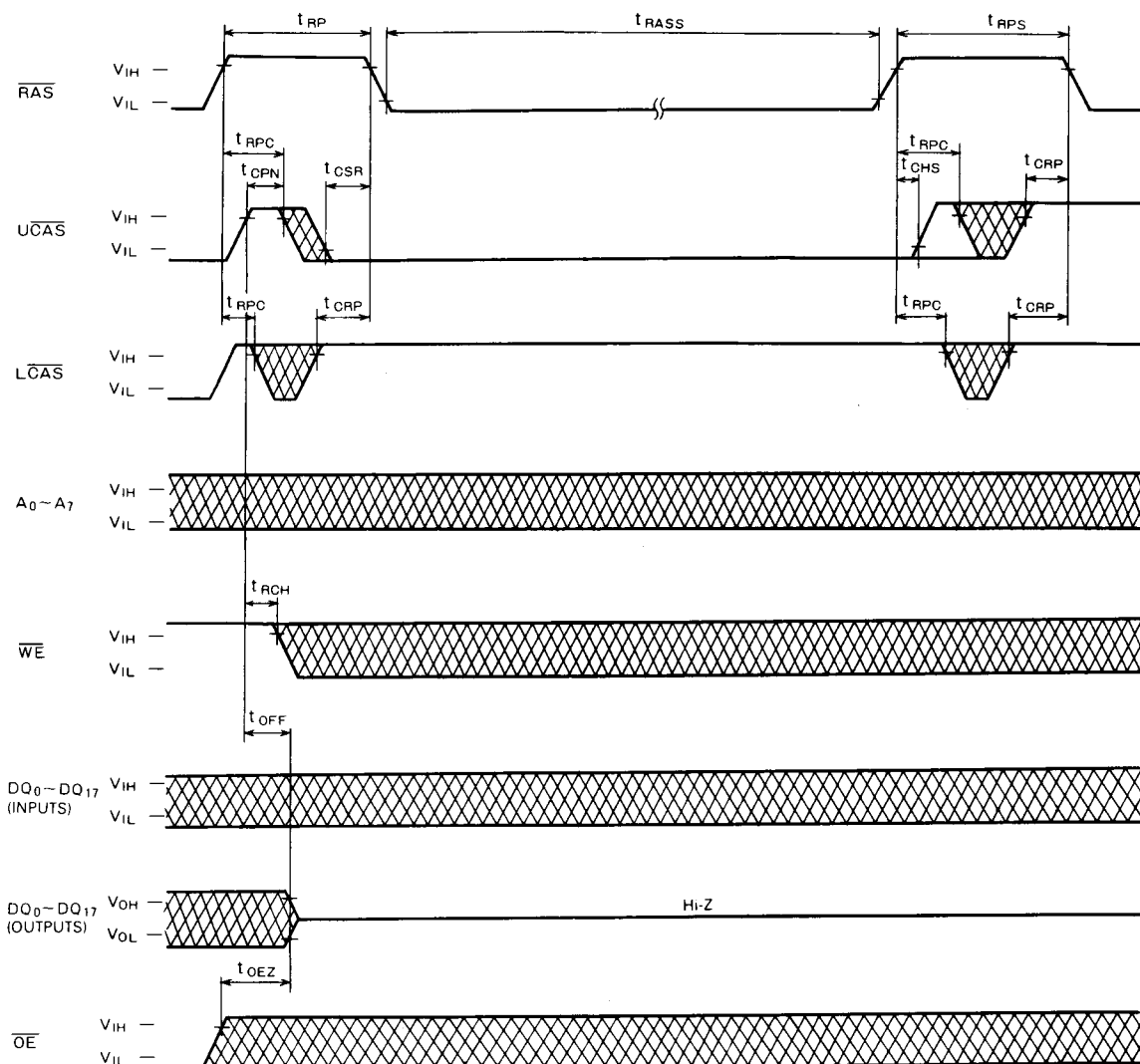


FAST PAGE MODE 1179648-BIT(65536-WORD BY 18-BIT)DYNAMIC RAM

CBR Self-Refresh Cycle (Note 28)



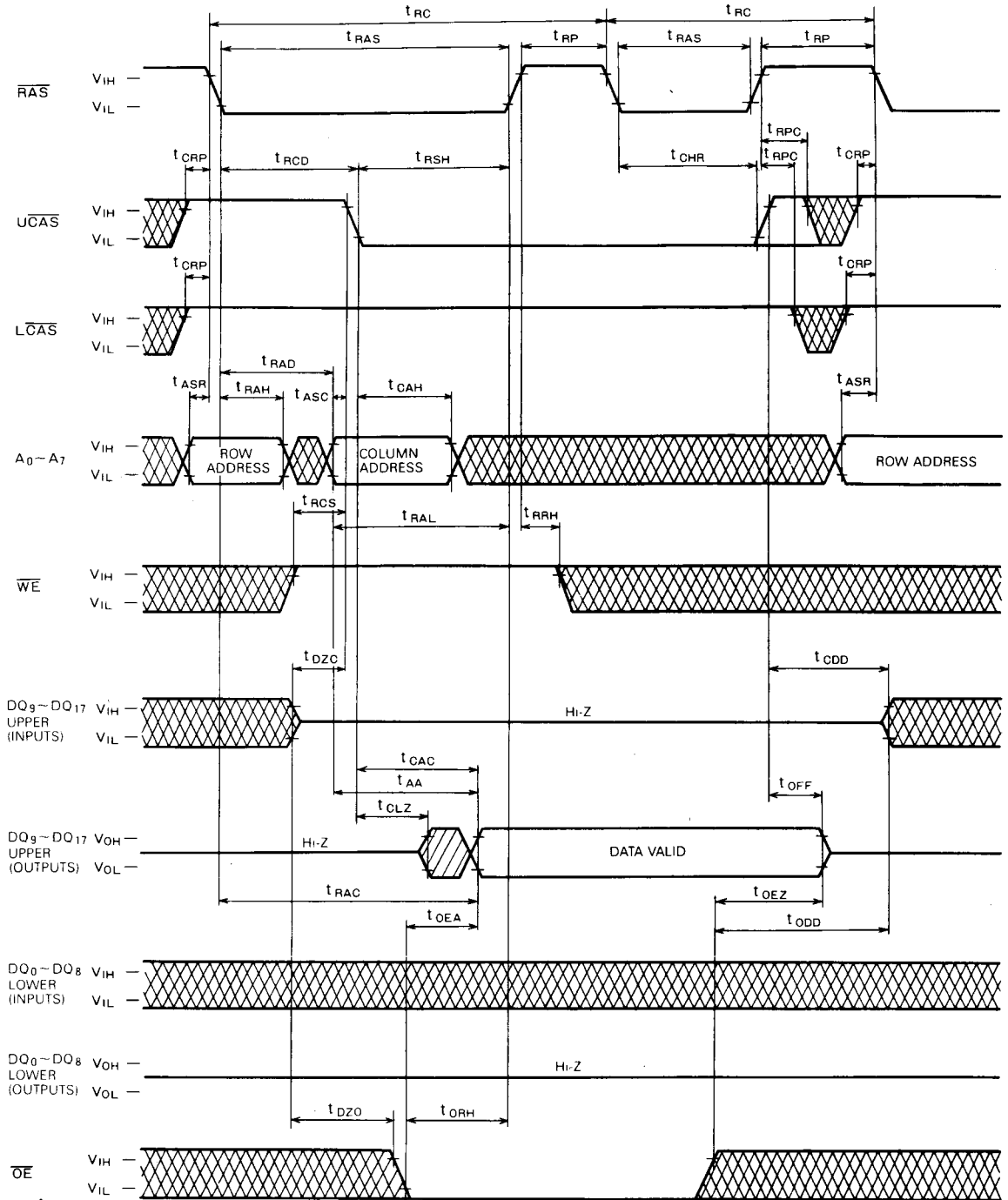
- Note 28:
1. When the \overline{RAS} only Refresh is used in the normal Read/Write cycle, the \overline{RAS} Only Refresh cycles must be completed for all row of 256 cycles no later than 4ms after the CBR Self Refresh exit.
 2. When the distributed CBR Refresh is used in the normal Read/Write cycles, the CBR Refresh cycles must start no later than 125 μ s after the CBR Self Refresh exit.
 3. When the Burst CBR Refresh is used in the normal Read/Write cycles, the Burst CBR Refresh cycles must be completed for 256 cycles no later than 4ms after the CBR Self Refresh exit.

FAST PAGE MODE 1179648-BIT(65536-WORD BY 18-BIT)DYNAMIC RAM**Upper (Lower) CBR Self Refresh Cycle** (Note 29)

- Note 29: 1. When the $\overline{\text{RAS}}$ only Refresh is used in the normal Read/Write cycle, the $\overline{\text{RAS}}$ Only Refresh cycles must be completed for all row of 256 cycles no later than 4ms after the CBR Self Refresh exit.
2. When the distributed CBR Refresh is used in the normal Read/Write cycles, the CBR Refresh cycles must start no later than 125 μ s after the CBR Self Refresh exit.
3. When the Burst CBR Refresh is used in the normal Read/Write cycles, the Burst CBR Refresh cycles must be completed for 256 cycles no later than 4ms after the CBR Self Refresh exit.

FAST PAGE MODE 1179648-BIT(65536-WORD BY 18-BIT)DYNAMIC RAM

Hidden Refresh Cycle (Upper (Lower) Byte Read) (Note 31)

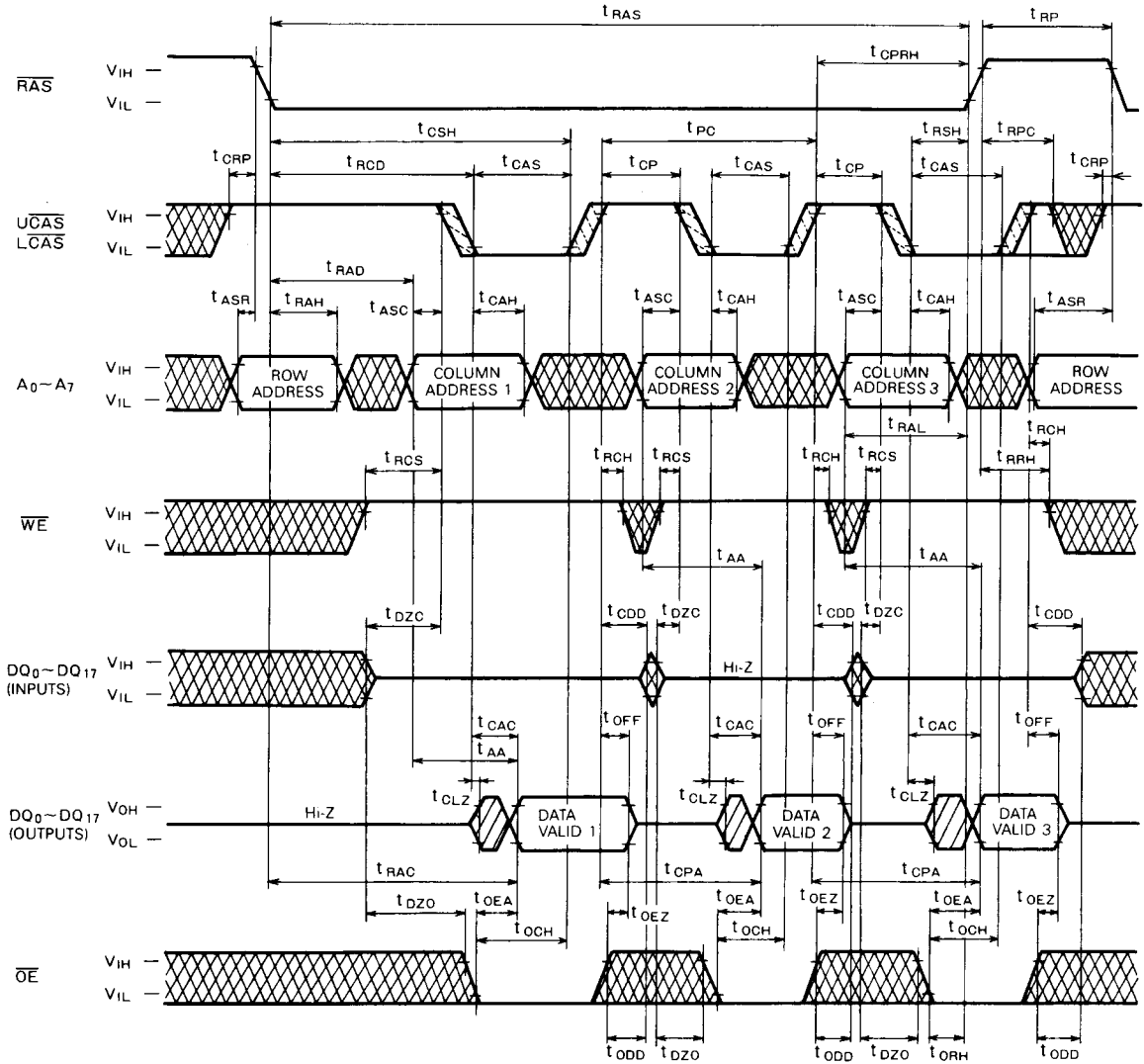


Note 31: Early write, delayed write, read modify write cycle is applicable instead of read cycle.
Timing requirements and output state are the same as that of each cycle shown above.

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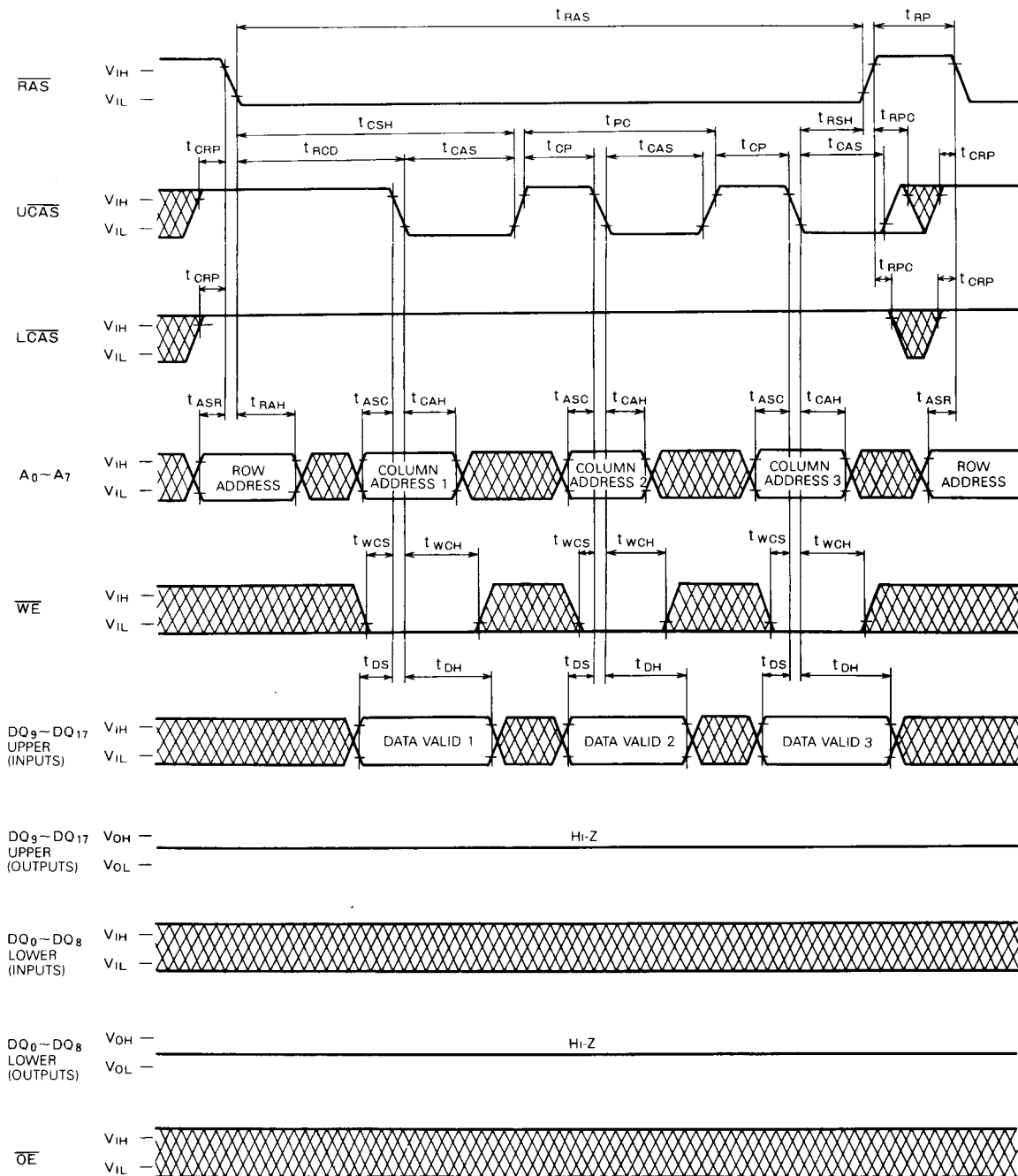
FAST PAGE MODE 1179648-BIT(65536-WORD BY 18-BIT)DYNAMIC RAM

Fast Page Mode Read Cycle



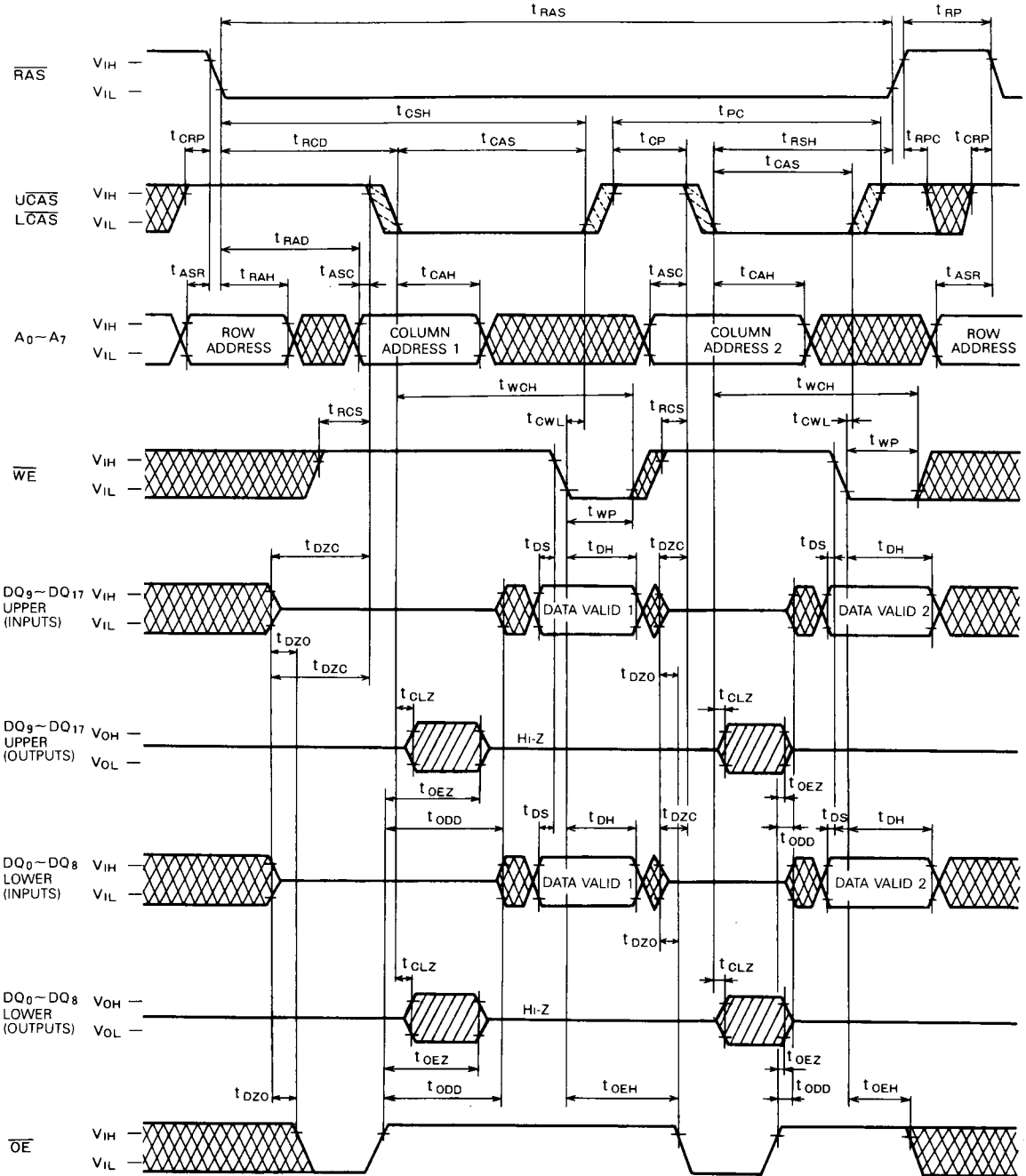
FAST PAGE MODE 1179648-BIT(65536-WORD BY 18-BIT)DYNAMIC RAM

Fast Page Mode Upper (Lower) Byte Early Write Cycle



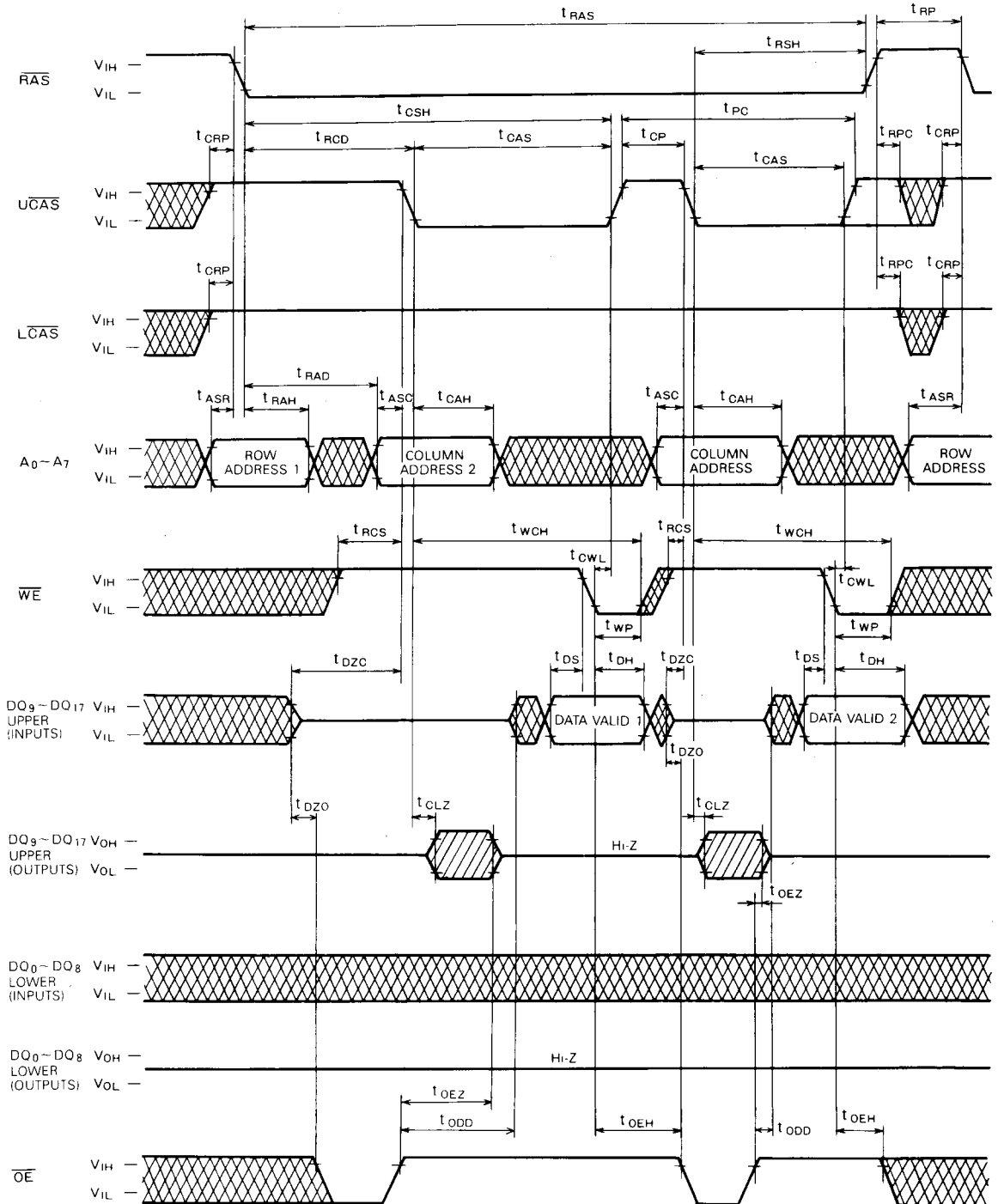
FAST PAGE MODE 1179648-BIT(65536-WORD BY 18-BIT)DYNAMIC RAM

Fast page Mode Delayed Write Cycle



FAST PAGE MODE 1179648-BIT(65536-WORD BY 18-BIT)DYNAMIC RAM

Fast Page Mode Upper (Lower) Byte Delayed Write Cycle



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FAST PAGE MODE 1179648-BIT(65536-WORD BY 18-BIT)DYNAMIC RAM

Fast Page Mode Read Modify Write Cycle

